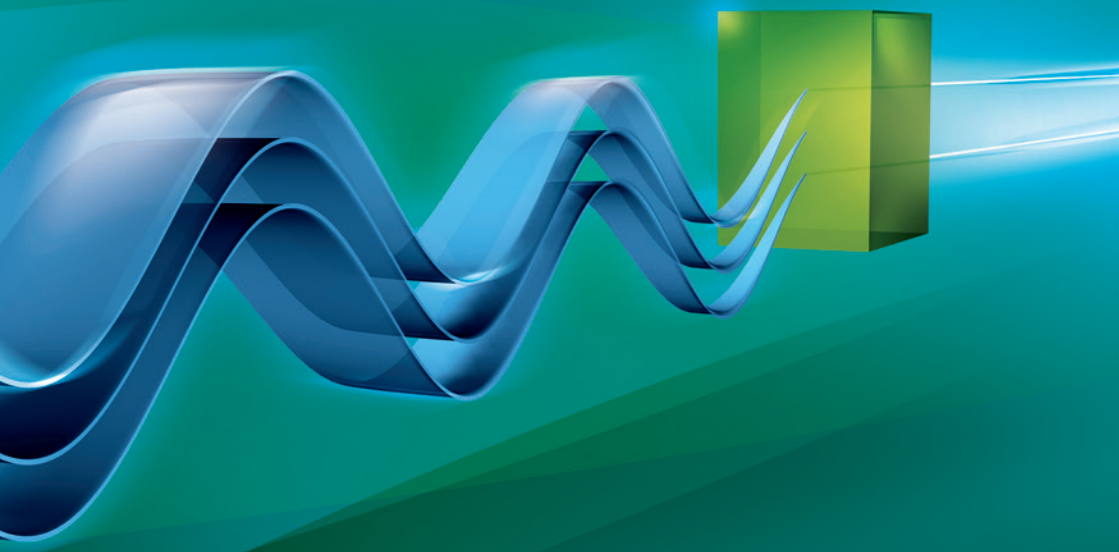


International Exhibition and Conference
for Power Electronics, Intelligent Motion,
Renewable Energy and Energy Management
Nuremberg, 5–7 June 2018

Messebegleiter 2018

Exhibition guide 2018



Auf einen Blick

Termin/Ort

05. – 07.06.2018

Messezentrum Nürnberg

Öffnungszeiten

Dienstag, 05.06.2018 09:00 – 17:00 Uhr

Mittwoch, 06.06.2018 09:00 – 17:00 Uhr

Donnerstag, 07.06.2018 09:00 – 17:00 Uhr

PCIM Europe 2018 im Internet

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5 – 7 June 2018

Exhibition Center Nuremberg

Opening hours

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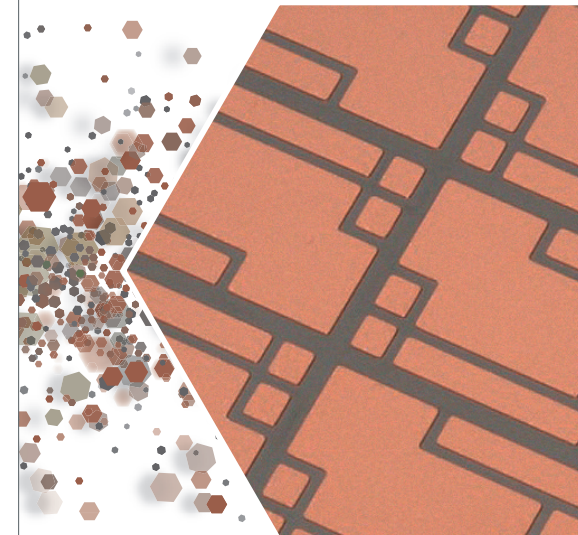
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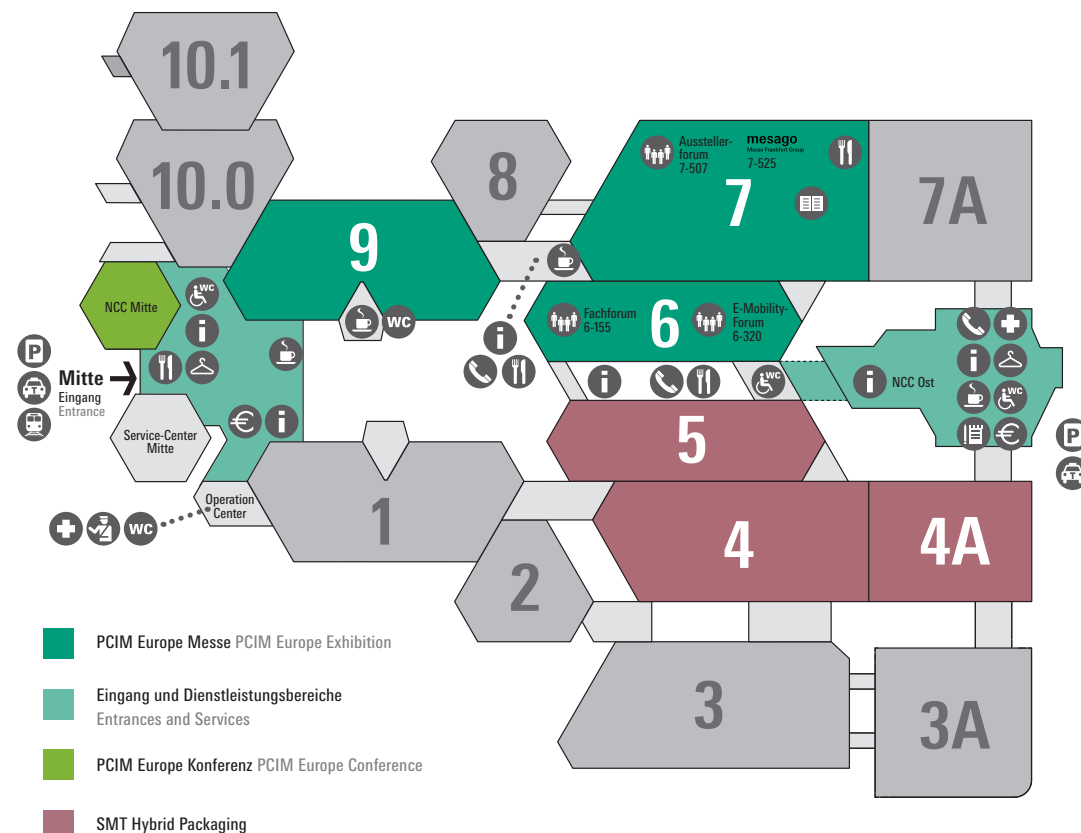
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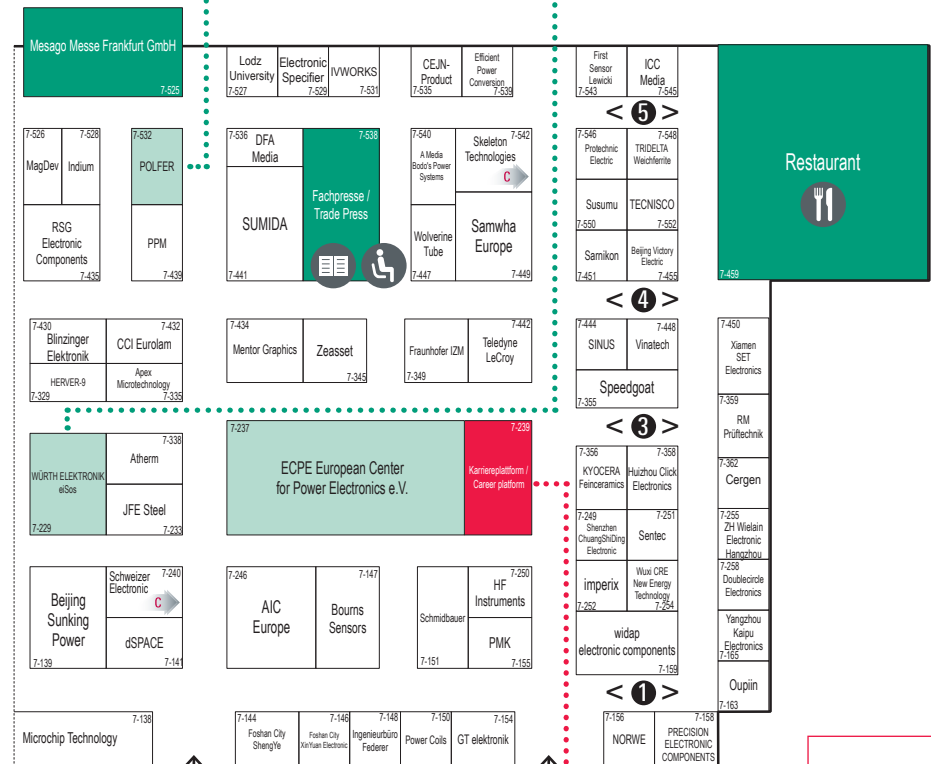
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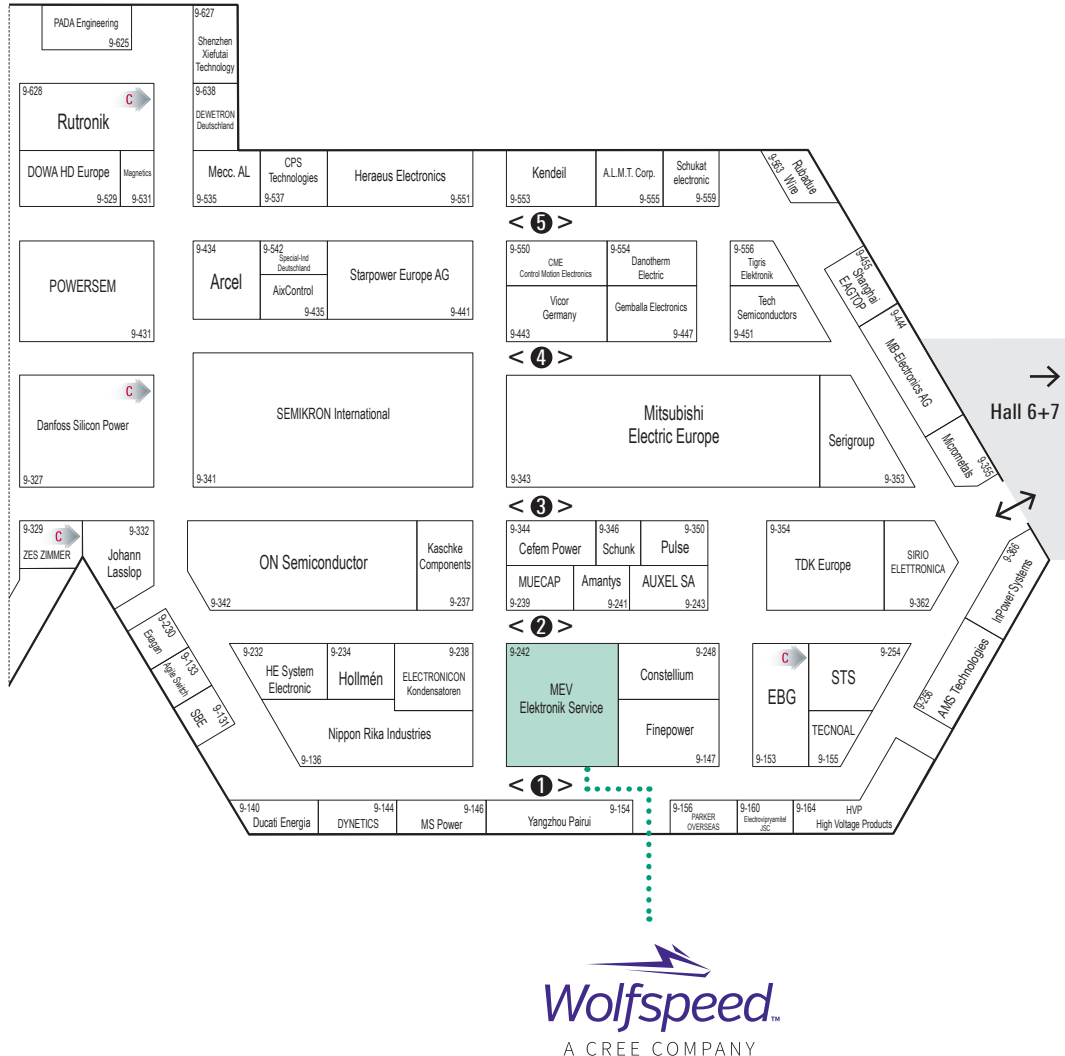
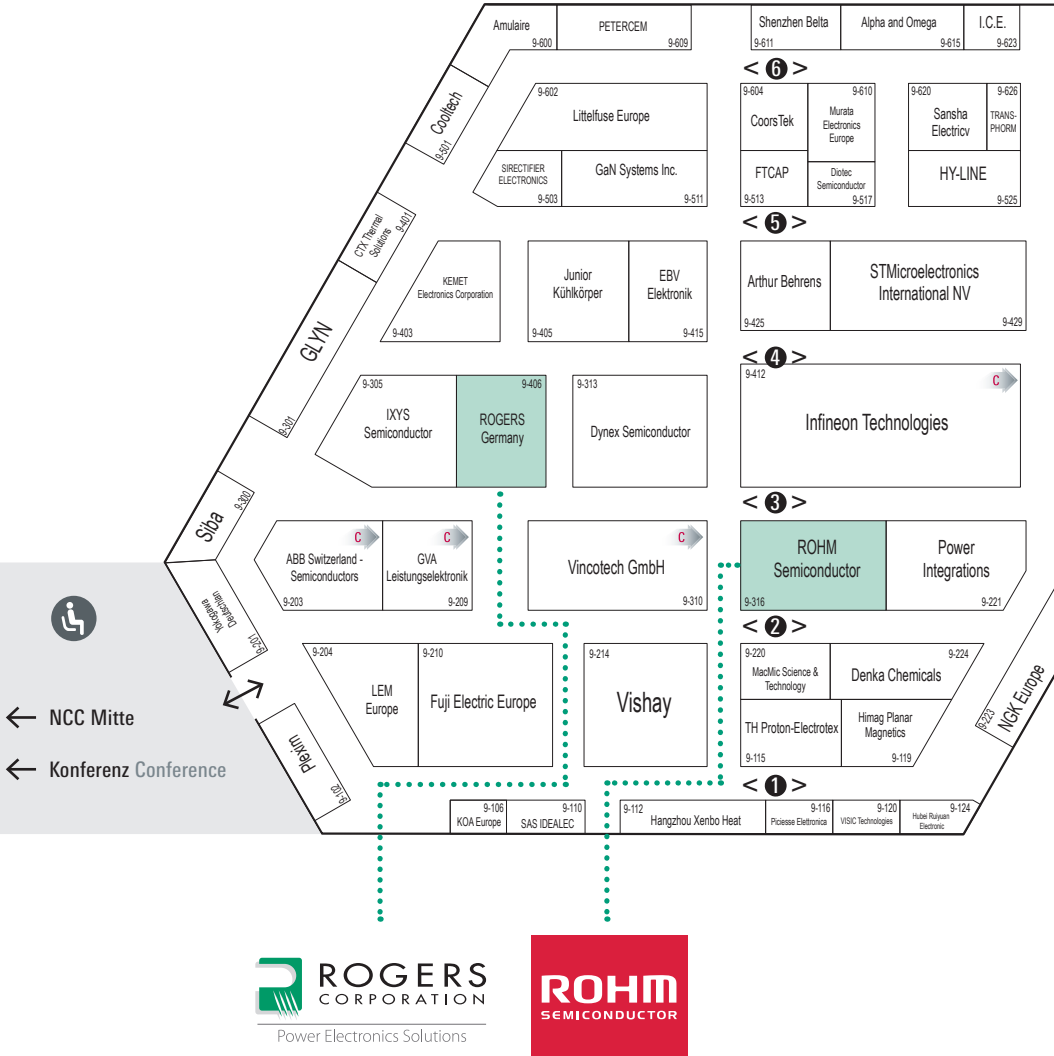
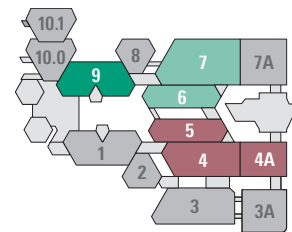


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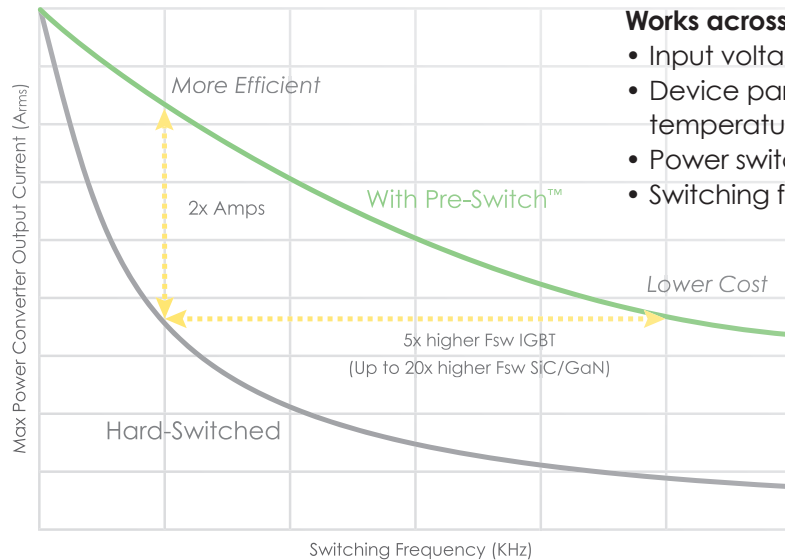
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Halle 7, Stand 507 hall 7, booth 507

Dienstag, 05.06.2018 Tuesday, 5 June 2018

10:00 – 10:20	Wolfspeed, Edgar Ayerbe Wolfspeed Introduces the Industry's Lowest On Resistance and Lowest Switching Losses at 1200V	
10:20 – 10:40	Advanced Cooling Technologies Inc., Pete Ritt Thermal Management Solutions for Challenging Power Electronics Applications	
10:40 – 11:00	Exagan S.A., Eric Moreau Intelligent GaN Solution for Consumer, Industrial and Automotive Markets	
11:00 – 11:20	Shanghai EAGTOP Electronic Technology Co., Ltd., Carlo Cutting-Edge Film Capacitor Technology for EV	
11:20 – 11:40	DEWETRON GmbH, Michael Oberhofer Reliable Frequency Measurement for Precise Power Analysis	
11:40 – 12:00	Panasonic Automotive & Industrial Systems Europe GmbH, Francois Perraud GAN	
12:00 – 12:20	Bs&T Frankfurt am Main GmbH, JC Sun AC Loss Under Square Wave: BsT-SQ Drawing Herbert Curve	
12:20 – 12:40	Atherm, Darie Payerne Atherm, an Industrial Supplier of Cooling Solutions on Demand	
12:40 – 13:00	Power Design Technologies SA, Nicolas Videau PowerForge: A Power Converter Design Tool to Achieve Highly Competitive Multilevel Technology Products	
13:00 – 13:20	EPCOS AG, A TDK Group Company, Claas Rosenkötter High-Voltage Contactors from TDK for Disconnection of Batteries in Electrical Vehicles	
13:20 – 13:40	Tamura-Europe Ltd., Luc Colombel Gate Driver Module Solution / 3 level Inverter & SiC Econo-Dual Pack	
13:40 – 14:00	ON Semiconductor, Raghu Nathadi High Output Current Gate Drivers for High Voltage and High Power Applications such as UPS, Solar Inverters, Motor Drives, Traction Inverters, OBCs and PTC Heaters	
14:00 – 14:20	KEMET Electronics Corporation, Axel Schmidt Passive Components for Automotive Drive Applications	
14:20 – 14:40	Littelfuse Europe GmbH, Michael Ketterer SiC Power Device Technology and Packaging – Creating Cost-Effective and Highly Reliable High Power Solutions	
14:40 – 15:00	Schunk GmbH, Sandra Reisinger Graphite-Based Solutions for (Power) Electronics Cooling	
15:00 – 15:20	GaNSystems & POWERSEM GmbH, Charles Bailley, Kavita Soni GaN at its best...! Customized GaN Power Modules by GaN Systems and Powersem	
15:20 – 15:40	HY-LINE Power Components Vertriebs GmbH, Jochen Krause Welche Leistungselektronik bietet Vorteile für meine Anwendung? Auswahl von IPM oder IGBT+Treiber, Gehäuseformen, Kondensatoren	

Halle 7, Stand 507 hall 7, booth 507

Dienstag, 05.06.2018 Tuesday, 5 June 2018

15:40 – 16:00	EpiGaN nv, Markus Behet How GaN will Dislodge Si-Based Technologies in Power & RF	
16:00 – 16:20	Danfoss Silicon Power GmbH, Matthias Beck DCM 1000 - Next Generation Automotive Power Module Platform	
16:20 – 16:40	Analog Devices GmbH, Bill Slattery The Mixed-Signal Challenges that WBG Switch Technologies Presents in Enabling the Next »Electric Revolution«	

Mittwoch, 06.06.2018 Wednesday, 6 June 2018

09:40 – 10:00	MacMic Science & Technology Co., Ltd., Kent Feng Cost Effective and High Performance Power Semiconductor for Inverter Welder and Power Source	
10:00 – 10:20	Indium Corporation, Andreas Karch, Karthik Vijay Improve Reliability and Bondline Control with InFORMs and Indalloy®276	
10:20 – 10:40	Rohde & Schwarz GmbH & Co KG, Thomas Rottach Choosing the Right Probing Solution and Oscilloscope for Power Converter Measurements	
10:40 – 11:00	A.L.M.T. Corp., Yuta Inoue High Performance Heatspreader Materials for Power Devices	
11:00 – 11:20	MB Electronic AG, Helko Meuche Innovative Magnetic Materials for Power Chokes and their Online Design Tools	
11:20 – 11:40	Hitachi Metals Europe GmbH, Hirotaka Satake Innovative Magnetic Materials for Electrification (Automotive, Industrial) from the Battery to the Final Product by Raw Materials & Components	
11:40 – 12:00	Mitsubishi Electric Europe B.V., Masaomi Miyazawa Highest PWM Switching Frequency with 1700V Si-IGBT Modules	
12:00 – 12:20	Vincotech GmbH, Baran Özbakir Cost and Efficiency Benchmark of Level-3 DC Fast-Charging SiC and Si Power Modules	
12:20 – 12:40	Dewesoft GmbH Bernhard Grasel Hochgenaue Leistungsmessung an Umrichtern muss nicht teuer sein	
12:40 – 13:00	POCO Holding Co., Ltd. Yunfan Zhang New Generation Powder Core - Help your CRM PFC & LLC Circuits Designing	
13:00 – 13:20	IQ evolution GmbH, Thomas Ebert 3D Metal-Printed Micro Coolers in the Field of Power Electronics	
13:20 – 13:40	SEMIKRON International GmbH, Timo Gassauer Efficient, Compact and Scalable DC Fast Charging Concept Based Upon 50kW Power Cell	
13:40 – 14:00	Fuji Electric Europe GmbH, Lukas Kleingrothe 450A/3.3kV 2in1 IGBT Module in Fuji Electric's High Power Next Core (HPnC) Package	
14:00 – 14:20	HEIDEN power GmbH, Kurt Reittberger Test & Simulation of Batteries and Fuel Cells	

Ausstellerforum Exhibitor forum

Halle 7, Stand 507 hall 7, booth 507

Mittwoch, 06.06.2018 Wednesday, 6 June 2018

14:20 – 14:40	Vacuumschmelze GmbH & Co. KG, Frank Schnelle	
	Nanocrystalline Cut Cores: New Technology for Significantly Reduced Core Losses	
14:40 – 15:00	Keysight Technologies Deutschland GmbH, Bernhard Holzinger, Ryo Takeda	
	WBG Power Circuit Simulation with Static/Dynamic/s-Parameter Characterization and Modeling	
15:00 – 15:20	Magnetics Inc., Donna Kepcia	
	The Impact of Core Structure on Inductor Performance	
15:20 – 15:40	MinDCet NV, Mike Wens	
	Driving GaN to the Limits: The GaNyMAD Module	
15:40 – 16:00	Diotec Semiconductor AG, Udo Steinebrunner	
	A Cost Effective, Temperature Compensated and ESD protected Power Supply for MicroControllers and Sensors using just Two Discrete Semiconductors	
16:00 – 16:20	ABB Switzerland Ltd, Raffael Schnell	
	Up to 30% more Current with ABB's Enhanced 3300V Trench and 6500V Planar IGBTs	
16:20 – 16:40	OPAL-RT EUROPE s.a.s., Timo Roesch	
	Power Electronic Applications to Benefit from Hardware-in-the-Loop Simulation	

Donnerstag, 07.06.2018 Thursday, 7 June 2018

09:40 – 10:00	First Sensor Lewicki GmbH, Benjamin Riedmüller	
	Technological Aspects for the Assembly of Highly Reliable Electronics – From Discrete Semiconductors to Complex Functional Modules	
10:00 – 10:20	Bose Research Private Limited, Supratim Basu	
	Latest Developments in Power Electronics Design: Si to SiC and GaN Devices in the Design of Converters Including Safety & EMC	
10:20 – 10:40	RECOM Power GmbH, Steve Roberts	
	Gate Driver Reference Design	
10:40 – 11:00	SBE, Inc., Andrew Hollyer	
	SBE Advanced DC Link Capacitors	
11:00 – 11:20	WAGO Kontakttechnik GmbH & Co. KG, Matthias Giese	
	Be Clever – Use Lever	
	Die neueste Generation der Hebelanschlusstechnik von WAGO	
11:20 – 11:40	Infineon Technologies AG, Vishal Jadhav	
	XHP (flexible High-Power Platform) for Optimizing Power Converter Designs	
11:40 – 12:00	STMICROELECTRONICS, Vladimir Scarpa	
	Power Semiconductor Solutions for EV Charging Stations	

Ausstellerforum Exhibitor forum

Halle 7, Stand 507 hall 7, booth 507

Donnerstag, 07.06.2018 Thursday, 7 June 2018

12:00 – 12:20	The MathWorks, Inc. & Speedgoat GmbH, Tony Lennon	
	MathWorks & Speedgoat will Discuss how Simulink Power Electronics Models Generate Floating-Point HDL Code for HIL Testing that Runs on the FPGA of Speedgoat Target Hardware to Achieve Simulation Time-Steps of 1 MHz and Faster	
12:20 – 12:40	3M Deutschland GmbH, Rajko Eichhorn	
	Integrierter Brandschutz – Lösch-Sicherungen mit 3M™ Novec™ High-Tech Flüssigkeit	
12:40 – 13:00	Sumitomo Electric Industries, Ltd., Hisashi Sakamoto	
	SiC V-Groove Trench MOSFETs (VMOSFETs) and Power Modules	
13:00 – 13:20	Trafor Europe, Guillaume Pasquet	
	Toroidal Coupled Inductors for Interleaved Multilevel Converters, How to Achieve Higher Performance and Cost Reduction Combining Optimized Design and Manufacturing Capability	
13:20 – 13:40	Siebel Elektronik GmbH, Henrik Siebel	
	High Isolating Power Supplies: Strategic Components in Power Electronics	
13:40 – 14:00	THALES DMS FRANCE, Sebastien Oge	
	Boosting the Performances of SiC Power Modules: Latest Achievements in Power Cycling Reliability and Thermal Performances	
14:00 – 14:20	RSG Electronic Components GmbH, Stefan Westerbecke	
	Balancing Custom-Design and Off-the-Shelf: When is a Standard Product Sufficient and when a Customer-Specific Development Pays off	
14:20 – 14:40	ROHM Semiconductor GmbH, Jochen Hueskens	
	SiC & Power Device Update ROHM Semiconductor	
14:40 – 15:00	Skeleton Technologies OÜ, Michael Liedtke	
	Next Generation Ultracapacitors - Finally!	
15:00 – 15:20	Powersys, Adrien Michel	
	Power Electronics Solution for Electric Vehicle Applications	
15:20 – 15:40	Mentor, a Siemens Business, Andreas Simon-Kajda	
	Calibration of a Multi-Source Component	
15:40 – 16:00	IXYS a Part of Littelfuse, Elmar Wisotzki	
	Input Rectifiers with Superior Commutation Ruggedness for Power Management – a Benchmark in Input Rectifier Technology	

Fachforum Industry forum

Fachforum Halle 6, Stand 155 Industry forum hall 6, booth 155

Dienstag, 05.06.2018 Tuesday, 5 June 2018

11:00 – 12:00	Infineon Technologies, Peter Friedrichs From Niche to Mainstream – SiC Power Devices as Enabler for Revolutionary Designs	🇬🇧
12:00 – 13:00	Power Systems Design, Ally Winning Challenges and Opportunities facing Power Supply Manufacturers over the next 5 years	🇬🇧
13:00 – 13:30	Yole Développement, Ana Villamor SiC and GaN, which Challenges Remain in the Road to Success?	🇬🇧
13:30 – 14:00	Fraunhofer EAS-IIS, Matthias Radecker Digital Control for Off-Line Power Supplies Using Digital Platform DP2	🇬🇧
14:00 – 14:30	TU Leoben, Helmut Weiss Measurements beyond Standard Tasks – 100kA Peak Current, 100MW Peak Power, etc.	🇬🇧
14:30 – 15:00	ENEA, Energy Technologies Department, Giuseppe Zummo Thermal Management of High Heat Flux Electronics with Mechanically Pumped Two-Phase Cooling	🇬🇧
15:00 – 15:45	HTV Halbleiter-Test & Vertriebs-GmbH, Holger Krumme Langzeitlagerung elektronischer Komponenten als Bestandteil einer vorausschauenden Obsoleszenzstrategie	🇩🇪

Mittwoch, 06.06.2018 Wednesday, 6 June 2018

10:00 – 11:30	Yole Développement, Mattin Grao Txapartegi and invited speakers Automotive Power Modules - Design Changes and Technology Innovations to Come?	🇬🇧
11:30 – 12:30	ECPE European Center for Power Electronics, Thomas Harder 15 Years ECPE Research Network	🇬🇧
12:30 – 13:20	Christian-Albrechts-University Kiel, Marco Liserre A Semi-Modular-Based and SiC-Based Smart Transformer	🇬🇧
13:30 – 14:30	A Media, Bodo's Power Systems, Bodo Arlt and invited speakers SiC – Devices for the Future Design	🇬🇧
14:30 – 15:30	A Media, Bodo's Power Systems, Bodo Arlt and invited speakers GaN – Devices for the Future Design	🇬🇧
15:30 – 16:00	Power Electronics Laboratory, EPFL, Drazen Dujic Electric Vehicles Charging – An Ultrafast Overview	🇬🇧

Fachforum Industry forum

Fachforum Halle 6, Stand 155 Industry forum hall 6, booth 155

Donnerstag, 07.06.2018 Thursday, 7 June 2018

10:00 – 10:30	Huawei, Petar Grbović New Passive Devices in Power Electronics - Nice to Have or a MUST?	🇬🇧
10:30 – 11:30	Bose Research, Supratim Basu Strategies for Increasing Efficiency, Controlling EMI and Reducing Cost in Practical Power Electronics Designs	🇬🇧
11:30 – 12:30	ECPE European Center for Power Electronics, Andreja Rojko, Lena Somschor Einführung Students Day	🇩🇪
12:30 – 13:00	Yole Développement, Milan Rosina How will Battery Packs Requirements impact Power Electronics Market?	🇬🇧
13:00 – 13:45	Silicon Catalyst, Raúl Camposano Realizing the New Growth Wave for Semiconductors Startups and Innovation in High Voltage and Power Density	🇬🇧
13:45 – 14:45	ROHM Semiconductor, Aly Mashaly SiC Solutions for Industrial and Automotive Applications	🇬🇧
14:45 – 15:15	KnowMade, Audrey Bastard SiC power devices and modules: Competitive landscape analysis from a patent perspective	🇬🇧
15:30 – 16:00	ECPE European Center for Power Electronics, Andreja Rojko, Lena Somschor Verlosung Students Day	🇩🇪

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E-Mobility-Forum Halle 6, Stand 320 E-Mobility forum hall 6, booth 320

Dienstag, 05.06.2018 Tuesday, 5 June 2018Kooperationspartner: ^{Elektronik}
automotive

10:00 – 10:30	Fraunhofer IISB, Bernd Eckardt Power Electronics for Future Mobility	
10:30 – 11:00	EBV Elektronik, Frank-Steffen Ruß Electrification and Autonomous Vehicle Systems: The Change of Electrical / Electronic Architecture	
11:00 – 11:30	On Semiconductor, Andrea Colognese Car Electrification: Semiconductor Power Technologies Meet Challenges and New Applications	
11:30 – 12:00	Rohm Semiconductor, Tomonori Hoki SiC Solutions for E-Mobility	
12:00 – 12:30	Schunk, Sandra Reisinger Latent Heat Carbon Solutions for E-Mobility	
14:00 – 14:30	Valeo, Ullus Klappach Technical Edge and Future Evolution of Onboard Charger	
14:30 – 15:00	Qualcomm, Nick Keeling Dynamic Electric Vehicle Charging: An Innovation Story	
15:00 – 15:30	Infineon Technologies, Uwe Kirchner, Bernhard Stiller Semiconductor Solutions for the Automotive Onboard Charger Applications	
15:30 – 16:00	Rutronik, Andreas Mangler Thermal Management of Lithium-Ions Cells in Battery Packs – Key Element of Functional Safety in E-Mobility Applications	
16:30 – 17:00	Mitsubishi Electric Europe, Khalid Hussein Power Semiconductors for E-Mobility – Securing Mature Solutions for Rising Technical Demands	

Mittwoch, 06.06.2018 Wednesday, 6 June 2018Kooperationspartner: ^{Elektronik}
automotive

10:00 – 10:30	Fraunhofer IISB, Bernd Eckardt Power Electronics for Future Mobility	
10:30 – 11:00	Rutronik, Andreas Mangler Thermal Management of Lithium-Ions Cells in Battery Packs – Key Element of Functional Safety in E-Mobility Applications	
11:00 – 11:30	On Semiconductor, Andrea Colognese Car Electrification: Semiconductor Power Technologies Meet Challenges and New Applications	

E-Mobility-Forum Halle 6, Stand 320 E-Mobility forum hall 6, booth 320

Mittwoch, 06.06.2018 Wednesday, 6 June 2018Kooperationspartner: ^{Elektronik}
automotive

11:30 – 12:00	Rohm Semiconductor, Tomonori Hoki SiC Solutions for E-Mobility	
12:00 – 12:30	Schunk, Sandra Reisinger Latent Heat Carbon Solutions for E-Mobility	
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15:30 – 16:00	EBV Elektronik, Frank-Steffen Ruß Electrification and Autonomous Vehicle Systems: The Change of Electrical / Electronic Architecture	
16:30 – 17:00	Mitsubishi Electric Europe, Khalid Hussein Power Semiconductors for E-Mobility – Securing Mature Solutions for Rising Technical Demands	

Donnerstag, 07.06.2018 Thursday, 7 June 2018

10:00 – 10:20	GaN Systems, Jim Witham Transforming the Automotive World with Smaller, Lower Cost, More Efficient Power Electronics	
10:20 – 10:40	Power Integrations, Michael Hornkamp SCALE-iDriver and FluxLink Technology in Automotive Applications	
10:40 – 11:00	Hollmén, Simon Wright Solve Your Thermal Challenges with Laser	
11:00 – 11:20	Mersen France SB, Pierrick Gueguen DC Hybrid Over-Current Protection and Safety Devices	
11:20 – 11:40	COOLTECH, Andrea Debbia Liquid Cooled Cold Plates for Electrical Mobility	
11:40 – 12:00	Hitachi Europe, Chris White Hitachi High Performance Power Modules for Electric Vehicles: IGBT, SiC MOS and Beyond	
12:00 – 12:20	Danfoss Silicon Power, Michael Tønnes E-Mobility Shapes Power Electronics Packaging Trends	

E-Mobility-Forum E-Mobility Forum

E-Mobility-Forum Halle 6, Stand 320 E-Mobility forum hall 6, booth 320

Donnerstag, 07.06.2018 Thursday, 7 June 2018

12:40 – 13:00	CYG Wayon Circuit Protection, Stephen Wu Super Junction MOSFET Solution for Automotive Charging Pile	🇬🇧
13:00 – 13:20	Magnetics, Donna Kepcia Low Loss, Concentrated Power. Magnetics Introduces High Reliability, Cost-Effective Materials and Shapes for Automotive Applications	🇬🇧
13:20 – 14:00	ETI Elektroelement, Mitja Koprivšek Advanced Solutions in Over-Current Protection of HVDC Circuit of Battery-Powered Electric Vehicle	🇬🇧
14:00 – 14:20	ENEA, Giuseppe Zummo Thermal Management of High Heat Flux Components in Electric Vehicles (EV and HEV) with Mechanically Pumped Two-Phase Cooling	🇬🇧
14:20 – 14:40	Toyochem, Kaori Nakamura Highly Flexible Thermally Conductive Adhesive Sheets for Electronic Devices	🇬🇧
14:40 – 15:00	Infineon Technologies, Martin Schulz Electrifying Urban Transportation	🇬🇧
15:00 – 15:20	Amosense, Yang Jaesuk Ceramic Substrates for Power Semiconductor and Thermal Solution for Power Electronic Devices	🇬🇧
15:20 – 15:40	Tech Mount, Roger Chen Cost-Effective Common Mode Filter for E-Mobility	🇬🇧
15:40 – 16:00	Shenzhen BYD Microelectronics, Miaopan Liu E-mobility as a challenge for power module manufacturers in the automotive industry: Cost vs. Capacity	🇬🇧

Optimierte Kühlung

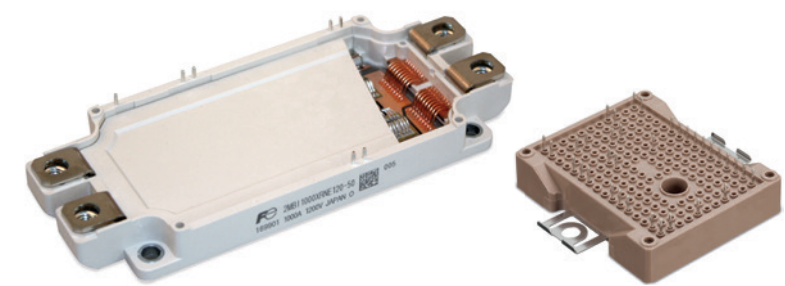
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Keynotes:



Tuesday, 5 June 2018

Electric Vehicles Charging – An Ultrafast Overview

Prof. Dr. Drzen Dujic, Power Electronics Laboratory, EPFL, Lausanne



Wednesday, 6 June 2018

New Passive Devices in Power Conversion – Nice to Have or a MUST?

Dr. Petar J. Grbović, Huawei Technologies, München



Thursday, 7 June 2018

Modular Multilevel Submodules for Converters, from the State of the Art to Future Trends

Dipl.-Ing. Markus Billmann, Fraunhofer Institute IISB, Erlangen

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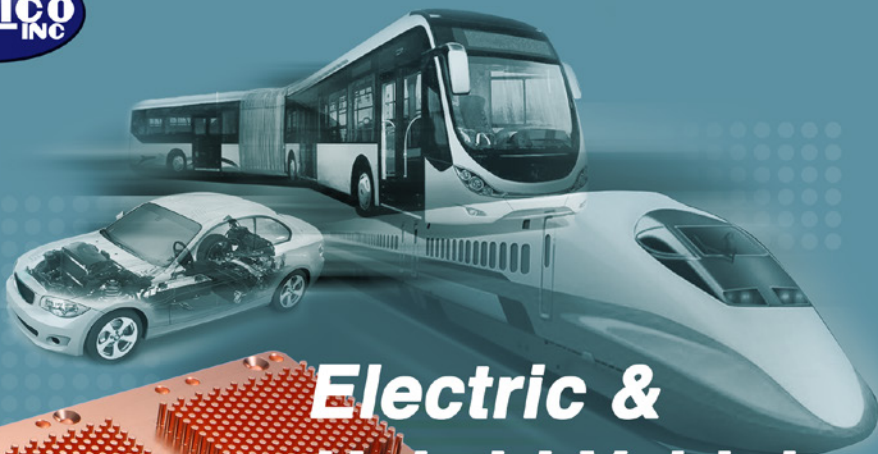
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